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# **IGBT**

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for resonant or soft switching applications. Incorporated into the device is a rugged co-packaged free wheeling diode with a low forward voltage.

#### **Features**

- Low Saturation Voltage using Trench with Fieldstop Technology
- Low Switching Loss Reduces System Power Dissipation
- Optimized for Low Case Temperature in IH Cooker Application
- Low Gate Charge
- These are Pb-Free Devices

#### **Typical Applications**

- Inductive Heating
- Consumer Appliances
- Soft Switching

#### **ABSOLUTE MAXIMUM RATINGS**

| Rating  | Symbol           | Value       | Unit |
|---|------------------|-------------|------|
| Collector-emitter voltage   | $V_{CES}$        | 1200        | V    |
| Collector current @ Tc = 25°C @ Tc = 100°C                                | I <sub>C</sub>   | 30<br>15    | A    |
| Pulsed collector current, T <sub>pulse</sub> limited by T <sub>Jmax</sub> | I <sub>CM</sub>  | 120         | Α    |
| Diode forward current<br>@ Tc = 25°C<br>@ Tc = 100°C                      | l <sub>F</sub>   | 30<br>15    | A    |
| Diode pulsed current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>     | I <sub>FM</sub>  | 100         | Α    |
| Gate-emitter voltage  | $V_{GE}$         | ±20         | V    |
| Power Dissipation @ Tc = 25°C @ Tc = 100°C                                | $P_{D}$          | 156<br>62.5 | W    |
| Operating junction temperature range                                      | TJ               | –55 to +150 | ç    |
| Storage temperature range   | T <sub>stg</sub> | -55 to +150 | °C   |
| Lead temperature for soldering, 1/8" from case for 5 seconds              | T <sub>SLD</sub> | 260         | °C   |

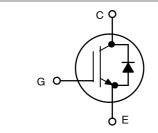
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

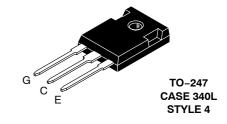


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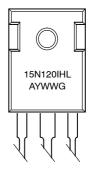
http://onsemi.com

15 A, 1200 V V<sub>CEsat</sub> = 1.8 V E<sub>off</sub> = 0.56 mJ





### **MARKING DIAGRAM**



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

#### **ORDERING INFORMATION**

| Device          | Package             | Shipping        |
|-----------------|---------------------|-----------------|
| NGTB15N120IHLWG | TO-247<br>(Pb-Free) | 30 Units / Rail |

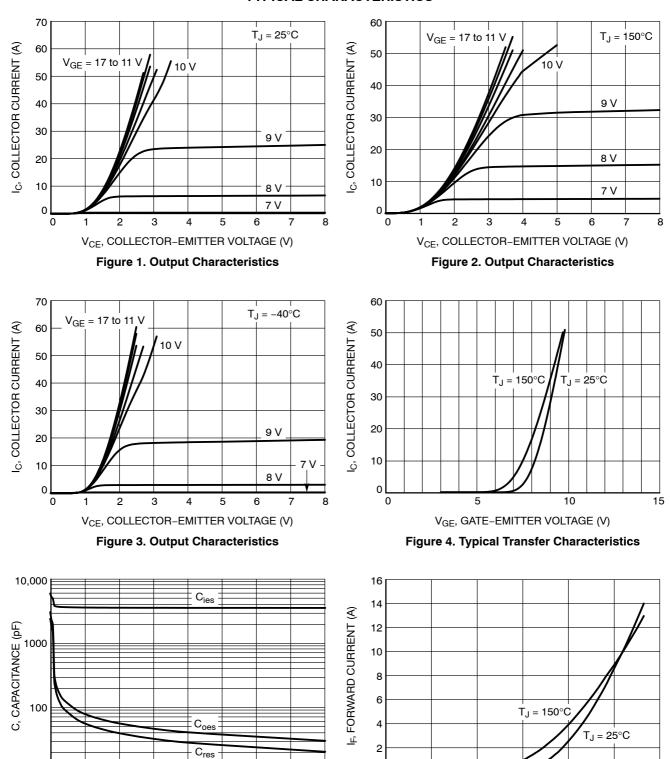
## THERMAL CHARACTERISTICS

| Rating   | Symbol        | Value | Unit |
|--|---------------|-------|------|
| Thermal resistance junction-to-case, for IGBT  | $R_{	hetaJC}$ | 0.8   | °C/W |
| Thermal resistance junction-to-case, for Diode | $R_{	hetaJC}$ | 2.0   | °C/W |
| Thermal resistance junction-to-ambient         | $R_{	hetaJA}$ | 60    | °C/W |

# **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified)

| Parameter   | Test Conditions  | Symbol               | Min    | Тур        | Max        | Unit |
|---|--|----------------------|--------|------------|------------|------|
| STATIC CHARACTERISTIC   |  |                      |        |            |            |      |
| Collector-emitter breakdown voltage, gate-emitter short-circuited   | $V_{GE} = 0 \text{ V, } I_{C} = 500  \mu\text{A}$  | V <sub>(BR)CES</sub> | 1200   | _          | -          | ٧    |
| Collector-emitter saturation voltage                                | V <sub>GE</sub> = 15 V, I <sub>C</sub> = 15 A<br>V <sub>GE</sub> = 15 V, I <sub>C</sub> = 15 A, T <sub>J</sub> = 150°C     | V <sub>CEsat</sub>   | -<br>- | 1.8<br>2.0 | 2.2        | V    |
| Gate-emitter threshold voltage                                      | $V_{GE} = V_{CE}, I_{C} = 150 \mu A$   | V <sub>GE(th)</sub>  | 4.5    | 5.5        | 6.5        | V    |
| Collector-emitter cut-off current, gate-<br>emitter short-circuited | V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V<br>V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V, T <sub>J =</sub> 150°C | I <sub>CES</sub>     | -<br>- | _<br>_     | 0.5<br>2.0 | mA   |
| Gate leakage current, collector-emitter short-circuited             | V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V  | I <sub>GES</sub>     | -      | _          | 100        | nA   |
| DYNAMIC CHARACTERISTIC  |  |                      |        |            |            |      |
| Input capacitance   |  | C <sub>ies</sub>     | -      | 3600       | -          | pF   |
| Output capacitance  | V <sub>CE</sub> = 20 V, V <sub>GE</sub> = 0 V, f = 1 MHz   | C <sub>oes</sub>     | -      | 88         | -          |      |
| Reverse transfer capacitance  | ]  | C <sub>res</sub>     | -      | 63         | -          |      |
| Gate charge total   |  | $Q_g$                |        | 160        |            | nC   |
| Gate to emitter charge  | V <sub>CE</sub> = 600 V, I <sub>C</sub> = 15 A, V <sub>GE</sub> = 15 V   | Q <sub>ge</sub>      |        | 30         |            |      |
| Gate to collector charge  |  | Q <sub>gc</sub>      |        | 73         |            |      |
| SWITCHING CHARACTERISTIC, INDUCT                                    | TIVE LOAD  |                      |        |            |            |      |
| Turn-off delay time   | T <sub>J</sub> = 25°C  | t <sub>d(off)</sub>  |        | 165        |            | ns   |
| Fall time   | $V_{CC} = 600 \text{ V}, I_{C} = 15 \text{ A}$ $R_{q} = 15 \Omega$   | t <sub>f</sub>       |        | 200        |            |      |
| Turn-off switching loss   | V <sub>GE</sub> = 0 V/ 15V   | E <sub>off</sub>     |        | 0.56       |            | mJ   |
| Turn-off delay time   | T <sub>J</sub> = 125°C   | t <sub>d(off)</sub>  |        | 180        |            | ns   |
| Fall time   | $V_{CC}$ = 600 V, $I_{C}$ = 15 A $R_{q}$ = 15 $\Omega$   | t <sub>f</sub>       |        | 260        |            |      |
| Turn-off switching loss   | V <sub>GE</sub> = 0 V/ 15V   | E <sub>off</sub>     |        | 0.95       |            | mJ   |
| DIODE CHARACTERISTIC  |  |                      |        |            |            |      |
| Forward voltage   | V <sub>GE</sub> = 0 V, I <sub>F</sub> = 15 A<br>V <sub>GE</sub> = 0 V, I <sub>F</sub> = 15 A, T <sub>J</sub> = 150°C       | V <sub>F</sub>       |        | 1.4<br>1.5 | 1.6        | V    |

#### TYPICAL CHARACTERISTICS



V<sub>CE</sub>, COLLECTOR-EMITTER VOLTAGE (V) Figure 5. Typical Capacitance

100

125

75

10

 $\label{eq:VF} V_F, \mbox{ FORWARD VOLTAGE (V)}$  Figure 6. Diode Forward Characteristics

0.75

1.25

1.50

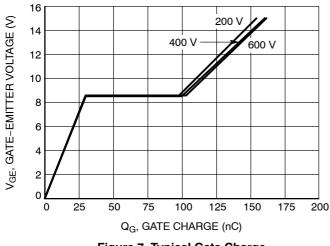
200

0

0.25

0.50

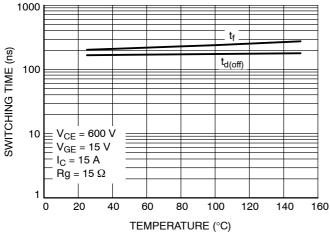
#### **TYPICAL CHARACTERISTICS**



(m V<sub>CE</sub> = 600 V Eoff, TURN-OFF SWITCHING LOSS 1.0  $V_{GE} = 15 V$  $I_C = 15 A$  $Rg = 15 \Omega$ 8.0 0.6 0.4 0.2 0 0 20 100 120 140 TEMPERATURE (°C)

Figure 7. Typical Gate Charge

Figure 8. Energy Loss vs. Temperature



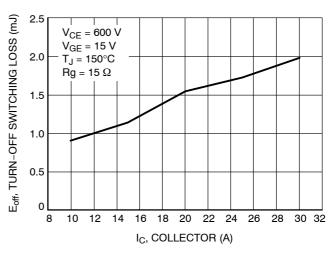
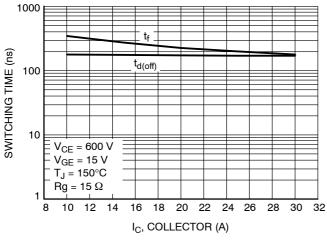


Figure 9. Switching Time vs. Temperature

Figure 10. Energy Loss vs. I<sub>C</sub>



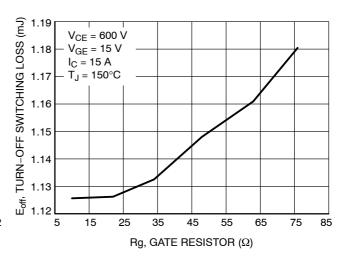


Figure 11. Switching Time vs. I<sub>C</sub>

Figure 12. Energy Loss vs. Rg

#### **TYPICAL CHARACTERISTICS**

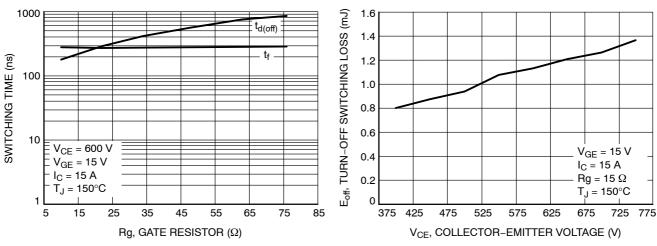


Figure 13. Switching Time vs. Rg

Figure 14. Energy Loss vs. V<sub>CE</sub>

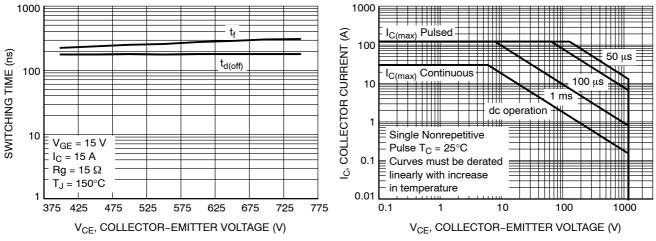


Figure 15. Switching Time vs. V<sub>CE</sub>

Figure 16. Safe Operating Area

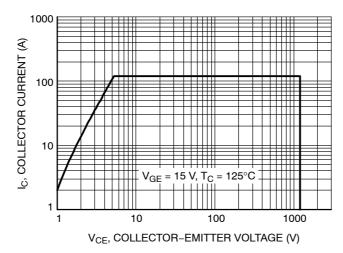


Figure 17. Reverse Bias Safe Operating Area

#### TYPICAL CHARACTERISTICS

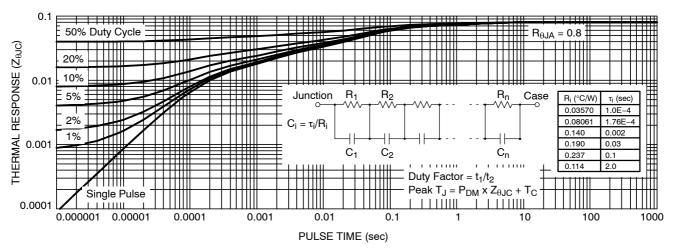


Figure 18. IGBT Transient Thermal Impedance

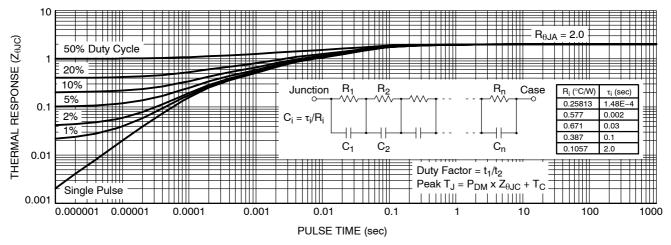


Figure 19. Diode Transient Thermal Impedance

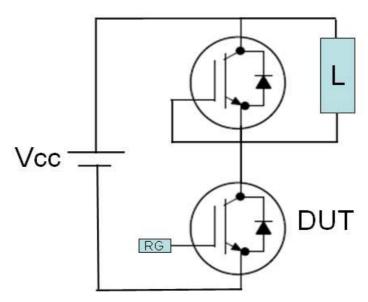


Figure 20. Test Circuit for Switching Characteristics

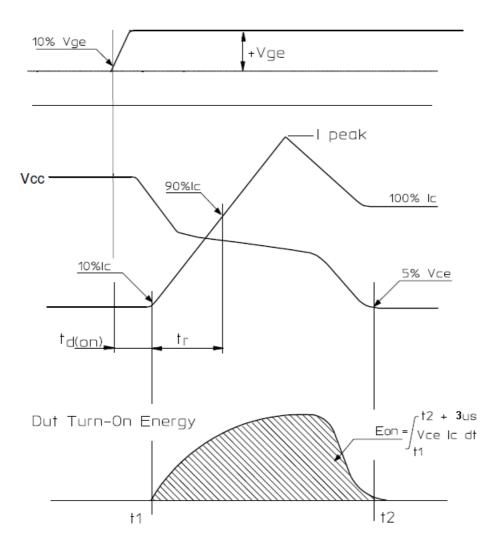


Figure 21. Definition of Turn On Waveform

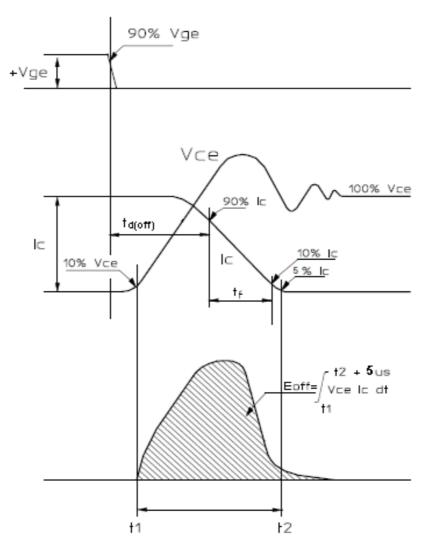
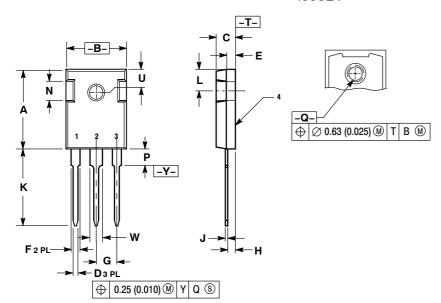


Figure 22. Definition of Turn Off Waveform

#### PACKAGE DIMENSIONS

TO-247 CASE 340L-02 **ISSUE F** 



#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.

|     | MILLIMETERS |       | INCHES    |       |  |
|-----|-------------|-------|-----------|-------|--|
| DIM | MIN         | MAX   | MIN       | MAX   |  |
| Α   | 20.32       | 21.08 | 0.800     | 8.30  |  |
| В   | 15.75       | 16.26 | 0.620     | 0.640 |  |
| С   | 4.70        | 5.30  | 0.185     | 0.209 |  |
| D   | 1.00        | 1.40  | 0.040     | 0.055 |  |
| E   | 1.90        | 2.60  | 0.075     | 0.102 |  |
| F   | 1.65        | 2.13  | 0.065     | 0.084 |  |
| G   | 5.45        | BSC   | 0.215     | BSC   |  |
| Н   | 1.50        | 2.49  | 0.059     | 0.098 |  |
| J   | 0.40        | 0.80  | 0.016     | 0.031 |  |
| K   | 19.81       | 20.83 | 0.780     | 0.820 |  |
| L   | 5.40        | 6.20  | 0.212     | 0.244 |  |
| N   | 4.32        | 5.49  | 0.170     | 0.216 |  |
| P   |             | 4.50  |           | 0.177 |  |
| Q   | 3.55        | 3.65  | 0.140     | 0.144 |  |
| U   | 6.15 BSC    |       | 0.242 BSC |       |  |
| W   | 2.87        | 3.12  | 0.113     | 0.123 |  |

STYLE 4: PIN 1. GATE

- 2. COLLECTOR 3. EMITTER
- 4 COLLECTOR

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